



2009 CALL FOR PARTICIPATION

IPC International Conferences on Lead-Free Electronics

May 13-15, 2009 ♦ Frankfurt, Germany
September 2009 ♦ Boston, MA
December 2009 ♦ Dallas, TX

The change to lead free solder has raised issues on the manufacture, processing, and reliability of electronic products. IPC is seeking speakers to participate conferences dedicated to lead-free and related issues.

Presentations from environmental managers and technical staff are sought on any relevant subjects, including:

Design for Reliability

- Alloy selection, composition effects (SAC305, 205, 105, SnCuNi, etc.)
- PCB FAB Specification
- Moisture Sensitivity

Processing

- Solderability
- Mixed solder alloys
- Soldering Profiles
- Assembly quality (intermetallics, voids)
- Repair/rework
- Inspection Criteria

Reliability

- Solder joints
- Printed Circuit Boards
- Components/packages/sockets
- Tin whiskers
- Repair/rework
- Accelerated life models

- Product Reliability Estimation
- High reliability/severe environment (automotive, aerospace, medical, etc.)

Test

- Test strategies, standards
- Failure acceleration methods
- Qualification procedures/data
- Solderability testing
- Drop/ flex/ thermal cycle/ vibration/ environmental testing
- Failure analysis
- X-ray
- T_g, TMA, T_d, T288, cT288, etc.

Regulations & Environment

- RoHS
- EuP
- Halogen Free
- REACH

These conferences offer time slots between 30-45 minutes long. Some presentations may be grouped together in a forum or panel discussion. To submit an abstract, please complete the second page of this form and include an abstract of 200-300 words along with a brief biography or you may provide the same information via e-mail to MichelleMichelotti@ipc.org.

Presentation materials must be non-commercial in nature, focusing on technology rather than a company's product.

EDUCATIONAL COURSES

Proposals are also solicited from individuals interested in teaching half-day workshops (three hours) to a class of up to 30 persons on topics in the field. Examples include; reliability, process issues, rework, plating and surface finishes, design for lead-free, design for recycling etc. Additional suggestions are also welcome.

An honorarium is offered to workshop instructors. A brief description and additional information on any such proposals should be submitted according to the guidelines for abstract submission i.e. by completion of the attached form.

SPONSORSHIPS AND TABLETOP EXHIBITS

Companies interested in information on the benefits associated with IPC event sponsorship or exhibiting in our tabletop exhibit, please email MichelleMichelotti@ipc.org.

REGISTRATION INFORMATION

If you would like to receive registration information on one of the IPC International Conferences on Lead-Free Electronic Components and Assemblies when available, please send your contact information to MichelleMichelotti@ipc.org.

Proposed Presentation (Please select which conferences you would like to present your abstract and/or course)

- April 22-24, 2009 ♦ Frankfurt, Germany
- September 2009 ♦ Boston, MA
- December 2009 ♦ Dallas, TX

Complete and mail, fax or e-mail this form with your biography and abstract/course descriptions to:

Attention: Lead-Free Electronics Conference
IPC – Association Connecting Electronics Industries
3000 Lakeside Drive, Suite 309 S
Bannockburn, IL 60015 - USA
Phone: (847) 597-2822 Fax: (847) 615-5622 / E-mail: MichelleMichelotti@ipc.org

Name _____

Company _____ Title _____

Street Address _____

City _____ State/Zip Code/Country _____

Phone _____ Fax _____

E-mail _____

Presentation Slot Desired: 30 minutes 45 minutes

On a separate page, please include your 200-300-word **abstract** describing the presentation you wish to have considered for the International Conferences on Lead-Free Electronics.

Workshop

On a separate page, please include your **course description** you wish to have considered for the International Conferences on Lead-Free Electronics.

Indicate the general area of Technology:

Design

Processing

Test

Regulations & Environment

Reliability

Other _____

Has this paper or course been presented before? Yes No

If yes, when and where? _____